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**WHAT IS CLAIMED IS:**

1. A ceramic heater comprising a heating element embedded in an insulating ceramic substrate, and a lead wire joined to a lead wire connection terminal via a brazing metal which contains a predominant amount of copper, wherein electrical continuity is established between the lead wire, lead wire connection terminal and heating element.

2. The ceramic heater as claimed in claim 1, wherein the brazing metal contains copper in an amount of not less than 85% by mass.

3. The ceramic heater as claimed in claim 1, wherein the brazing metal contains Ti or Si as an activation metal.

4. The ceramic heater as claimed in claim 2, wherein the brazing metal contains Ti or Si as an activation metal.

5. The ceramic heater as claimed in claim 3, wherein the Ti or Si content of the brazing metal is 0.1-5% by mass.

6. The ceramic heater as claimed in claim 4, wherein the Ti or Si content of the brazing metal is 0.1-5% by mass.

7. The ceramic heater as claimed in claim 1, comprising a pad formed on the lead wire so as to serve as a joining surface to be joined to the lead wire connection terminal, the lead wire being joined to the lead wire connection terminal via the pad.

8. The ceramic heater as claimed in claim 1, wherein the brazing metal joining the lead wire and the lead wire connection terminal is a layer having a thickness of 30-400  $\mu\text{m}$ .

9. The ceramic heater as claimed in claim 1, wherein the brazing metal joining the lead wire and the lead wire connection terminal is a layer having a thickness of 50-300  $\mu\text{m}$ .

10. The ceramic heater as claimed in claim 1, wherein the brazing metal joining the lead wire and the lead wire connection terminal is a layer having a thickness of 150-250  $\mu\text{m}$ .

11. The ceramic heater as claimed in claim 8, comprising an interjacent buffer plate formed of copper present in the layer of brazing metal joining the lead wire and the lead wire connection terminal, and the thickness of the layer of brazing metal includes that of the buffer plate formed of copper.

12. The ceramic heater as claimed in claim 9, comprising an interjacent buffer plate formed of copper present in the layer of brazing metal joining the lead wire and the lead wire connection terminal, and the thickness of the layer of brazing metal includes that of the buffer plate formed of copper.

13. The ceramic heater as claimed in claim 10, comprising an interjacent buffer plate formed of copper present in the layer of brazing metal

joining the lead wire and the lead wire connection terminal, and the thickness of the layer of brazing metal includes that of the buffer plate formed of copper.